

RADIATION SENSITIVE RESIN COMPOSITION

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Abstract of JP10319593

PROBLEM TO BE SOLVED: To make it possible to easily form a patternwise thin film superior in various characteristics, such as resistances to heat and solvents and transparency and low in dielectric constant with high sensitivity by forming the composition comprising a fluorinated copolymer, an acid generator, a cross-linking compound, and an organic solvent for dissolving these components.

SOLUTION: This radiation sensitive resin composition comprises (A) (a-1) hexafluoropropylene, (a-2) an unsaturated carboxylic acid and/or its anhydride, and (a-3) the fluorinated copolymer made from (a-1) an (a-2) and an unsaturated monomer copolymerizable with (a-1) and (a-2), (B) the acid generator to be allowed to generate an acid by irradiation with radiation, (C) the organic solvent for dissolving the components of (A), (B), and (C). This constitution permits this composition to be developed in an aqueous alkaline solution and to have high sensitivity and to easily form a patternwise thin film superior in resistances to heat and solvents and high in transparency and low in dielectric constant.

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